MOSFETs Silicon P-Channel MOS (U-MOSVI)

TPH1R712MD

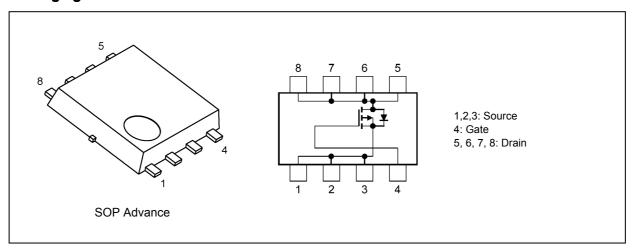
1. Applications

- Lithium-Ion Secondary Batteries
- · Power Management Switches

2. Features

- (1) Low drain-source on-resistance: $R_{DS(ON)} = 1.35 \text{ m}\Omega$ (typ.) ($V_{GS} = -4.5 \text{ V}$)
- (2) Low leakage current: $I_{DSS} = -10 \mu A \text{ (max) (V}_{DS} = -20 \text{ V)}$
- (3) Enhancement mode: V_{th} = -0.5 to -1.2 V (V_{DS} = -10 V, I_D = -1.0 mA)

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) (Ta = 25 °C unless otherwise specified)

Characteris	Symbol	Rating	Unit		
Drain-source voltage			V _{DSS}	-20	V
Gate-source voltage			V _{GSS}	±12	1
Drain current (DC)	(T _c = 25 °C)	(Note 1)	I _D	-60	Α
Drain current (pulsed)	(t = 1 ms)	(Note 1)	I _{DP}	-200	1
Power dissipation	(T _c = 25 °C)		P _D	78	W
Power dissipation	(t = 10 s)	(Note 2)	P _D	2.8]
Power dissipation	(t = 10 s)	(Note 3)	P _D	1.6	
Single-pulse avalanche energy		(Note 4)	E _{AS}	468	mJ
Single-pulse avalanche current			I _{AS}	-60	Α
Channel temperature			T _{ch}	150	°C
Storage temperature			T _{stg}	-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Start of commercial production



5. Thermal Characteristics

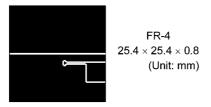
Characteristics			Symbol	Max	Unit
Channel-to-case thermal resistance	(T _c = 25 °C)		R _{th(ch-c)}	1.60	°C/W
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 2)	R _{th(ch-a)}	44.6	
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 3)	R _{th(ch-a)}	78.1	

Note 1: Ensure that the channel temperature does not exceed 150 °C.

Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 4: V_{DD} = -16 V, T_{ch} = 25 °C (initial), L = 100 $\mu H,\ I_{AS}$ = -60 A



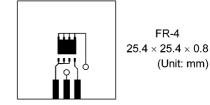


Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)

Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

6. Electrical Characteristics

6.1. Static Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±0.1	μА
Drain cut-off current	I _{DSS}	V _{DS} = -20 V, V _{GS} = 0 V	_	_	-10	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = -10 mA, V _{GS} = 0 V	-20	_	_	V
Drain-source breakdown voltage (Note 5)	V _{(BR)DSX}	I _D = -10 mA, V _{GS} = 8.0 V	-12	_	_	
Gate threshold voltage	V_{th}	V_{DS} = -10 V, I_{D} = -1.0 mA	-0.5	_	-1.2	
Drain-source on-resistance	R _{DS(ON)}	V _{GS} = -2.5 V, I _D = -30 A	_	2.0	2.7	mΩ
		V _{GS} = -4.5 V, I _D = -30 A	_	1.35	1.7	

Note 5: If a reverse bias is applied between gate and source, this device enters $V_{(BR)DSX}$ mode. Note that the drain-source breakdown voltage is lowered in this mode.

6.2. Dynamic Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz	_	10900	_	pF
Reverse transfer capacitance	C _{rss}		_	1550	_	
Output capacitance	C _{oss}		_	2010	_	
Switching time (rise time)	t _r	See Fig. 6.2.1.	_	14	_	ns
Switching time (turn-on time)	t _{on}		_	27	_	
Switching time (fall time)	t _f		_	512	_	
Switching time (turn-off time)	t _{off}		_	1620		

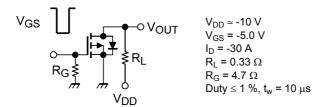


Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	$V_{DD} \approx -16 \text{ V}, V_{GS} = -5.0 \text{ V}, I_{D} = -60 \text{ A}$	_	182		nC
Gate-source charge 1	Q _{gs1}		_	23	_	
Gate-drain charge	Q_{gd}			56		

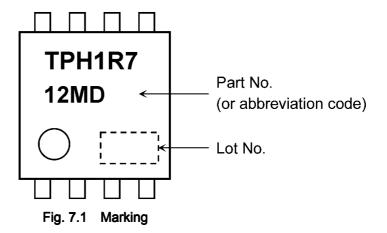
6.4. Source-Drain Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed)	(Note6)	I _{DRP}	_	-	-	-200	Α
Diode forward voltage		V _{DSF}	I _{DR} = -60 A, V _{GS} = 0 V			1.2	V

Note6: Ensure that the channel temperature does not exceed 150°C.



7. Marking



8. Characteristics Curves (Note)

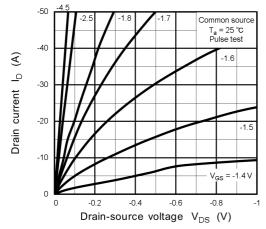


Fig. 8.1 I_D - V_{DS}

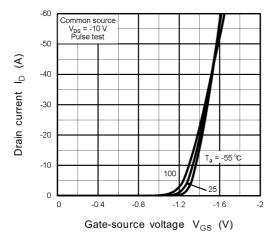


Fig. 8.3 $I_D - V_{GS}$

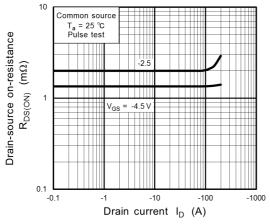


Fig. 8.5 R_{DS(ON)} - I_D

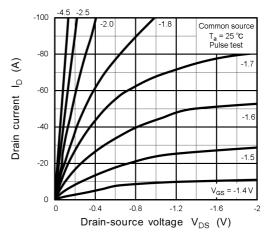


Fig. 8.2 I_D - V_{DS}

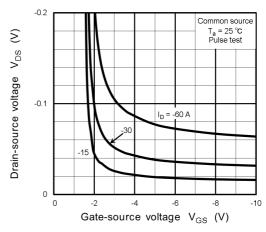


Fig. 8.4 V_{DS} - V_{GS}

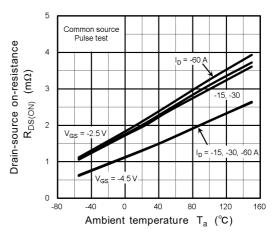


Fig. 8.6 R_{DS(ON)} - T_a

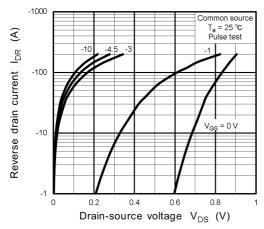


Fig. 8.7 IDR - VDS

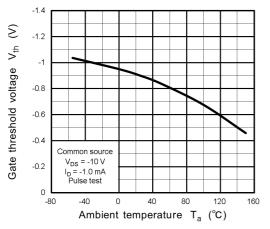


Fig. 8.9 V_{th} - T_a

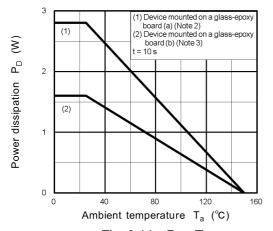


Fig. 8.11 P_D - T_a (Guaranteed Maximum)

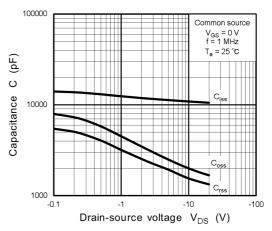


Fig. 8.8 Capacitance - V_{DS}

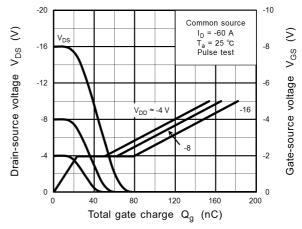


Fig. 8.10 Dynamic Input/Output Characteristics

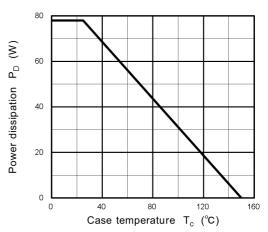


Fig. 8.12 P_D - T_c (Guaranteed Maximum)

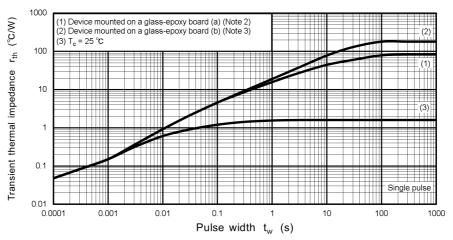


Fig. 8.13 r_{th} - t_w (Guaranteed Maximum)

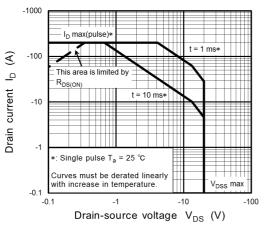


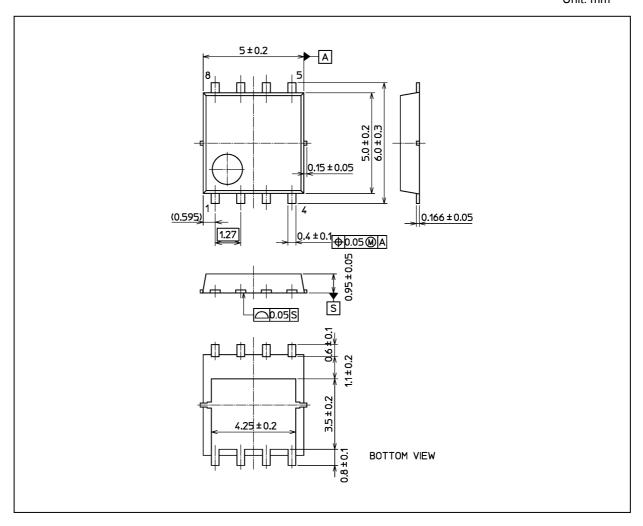
Fig. 8.14 Safe Operating Area (Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



Package Dimensions

Unit: mm



Weight: 0.069 g (typ.)

	Package Name(s)
TOSHIBA: 2-5Q1S	
Nickname: SOP Advance	

Rev.4.0



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